

Abstracts

New 3D TLM Condensed Node Structures for Improved Simulation of Conductor Strips

J.S. Nielsen and W.J.R. Hoefer. "New 3D TLM Condensed Node Structures for Improved Simulation of Conductor Strips." 1992 MTT-S International Microwave Symposium Digest 92.3 (1992 Vol. III [MWSYM]): 1221-1223.

This paper presents a set of modified condensed node TLM structures, compatible with the 3D TLM condensed node, that improve the modelling of conductor strips and provide a means of directly embedding lumped devices into the mesh. The improvement in accuracy is demonstrated by evaluating the propagation constant of a simulated microstrip line.

[Return to main document.](#)

Click on title for a complete paper.